



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al

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Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Thao X. Le

Title: **THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES**

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Honorable Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**REQUEST FOR RECONSIDERATION**

This Request for Reconsideration is being filed in response to the Office Action mailed on November 29, 2004.